

Gehäusemaßbilder

(Maße in mm, wenn nicht anders angegeben)

Package Outlines

(Dimensions in mm, unless otherwise specified)

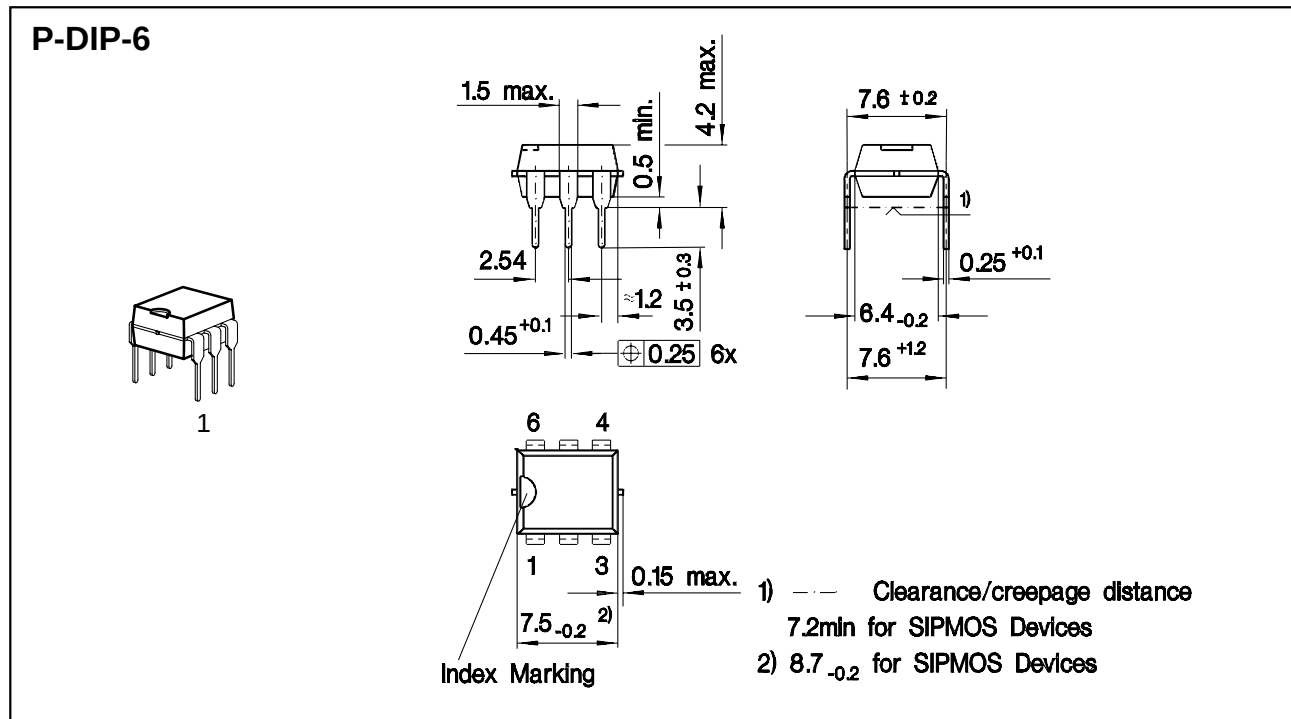


Bild 1

Figure 1

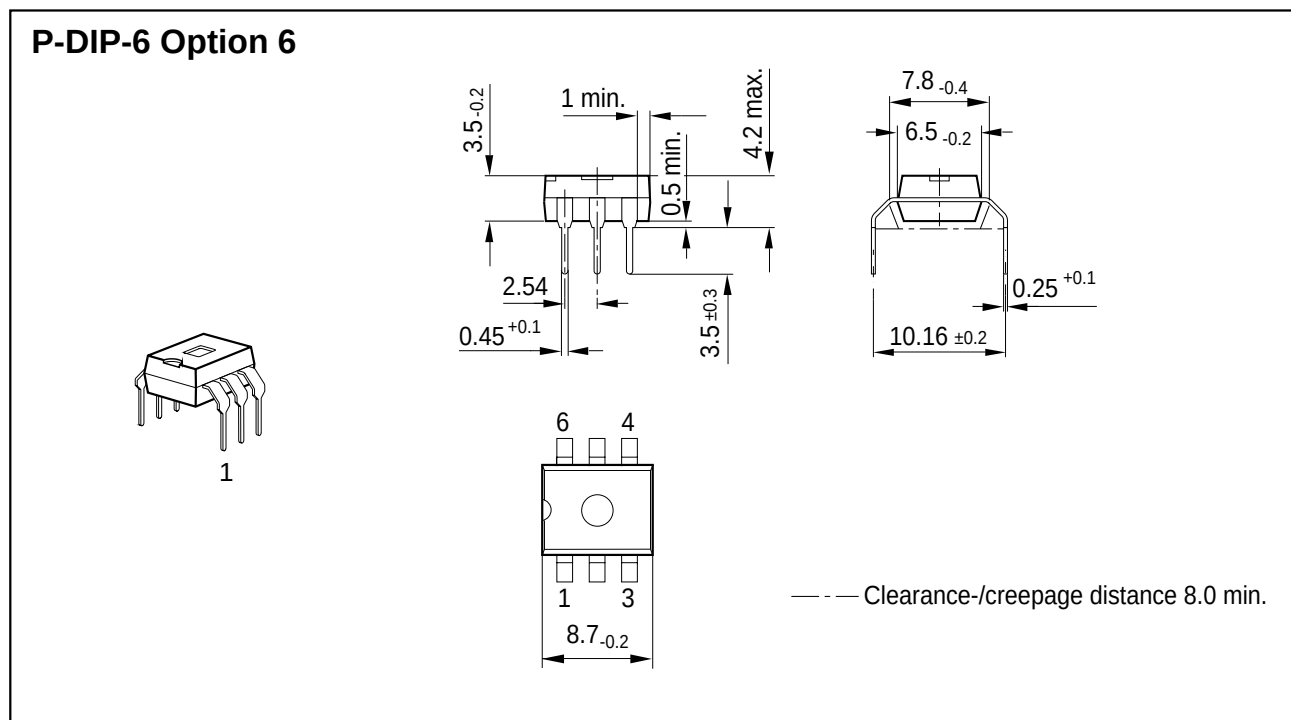


Bild 2

Figure 2

P-DIP-6 Option 7

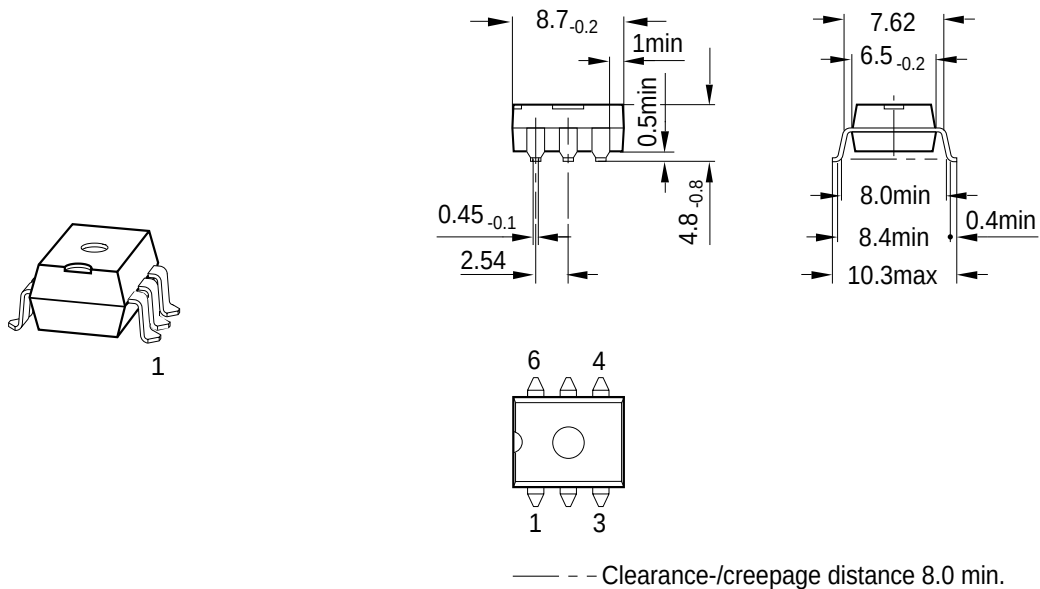


Bild 3

Figure 3

SOT-23 (SMD)

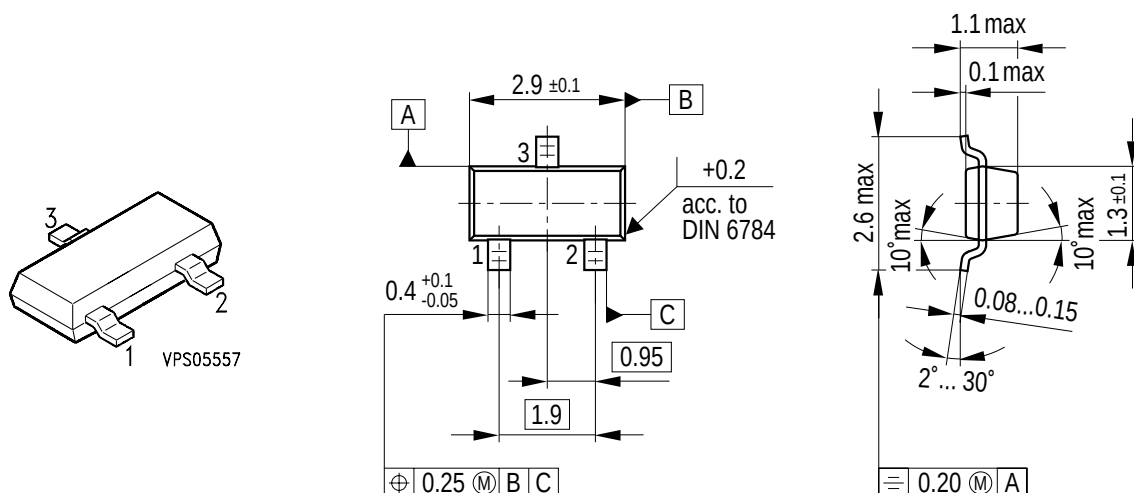


Bild 4

Figure 4

SOT-89 (SMD)

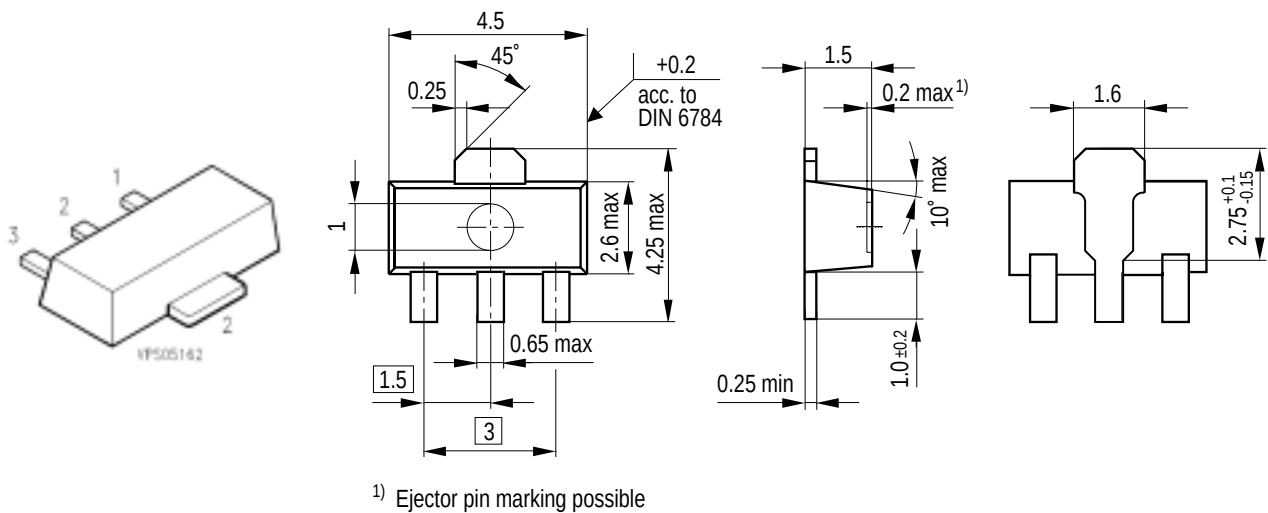


Bild 5

Figure 5

SOT-223 (SMD)

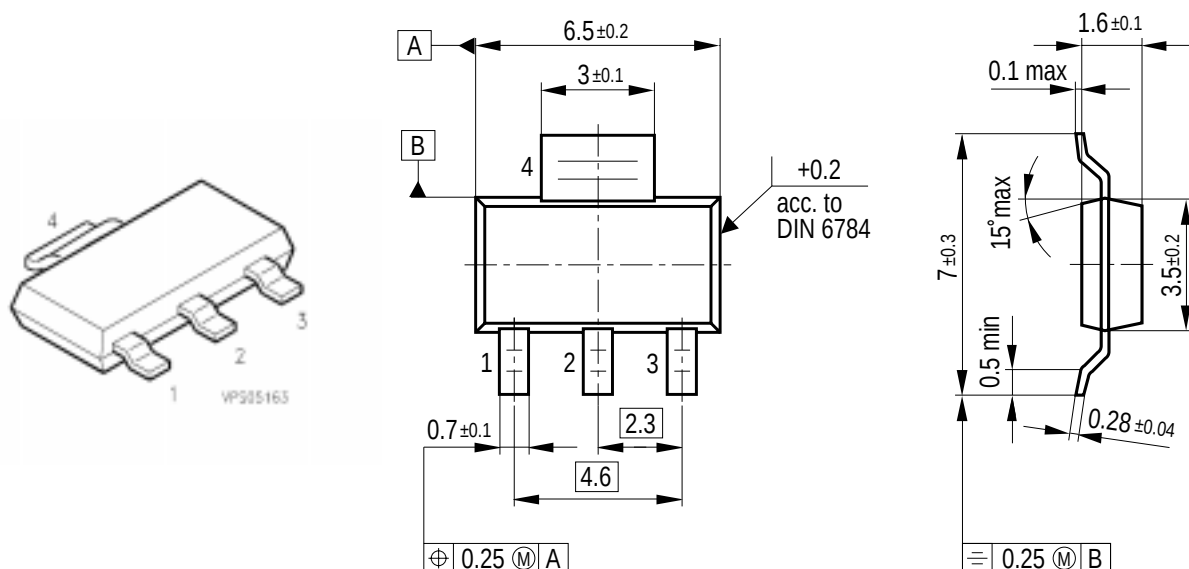


Bild 6

Figure 6

TO-92

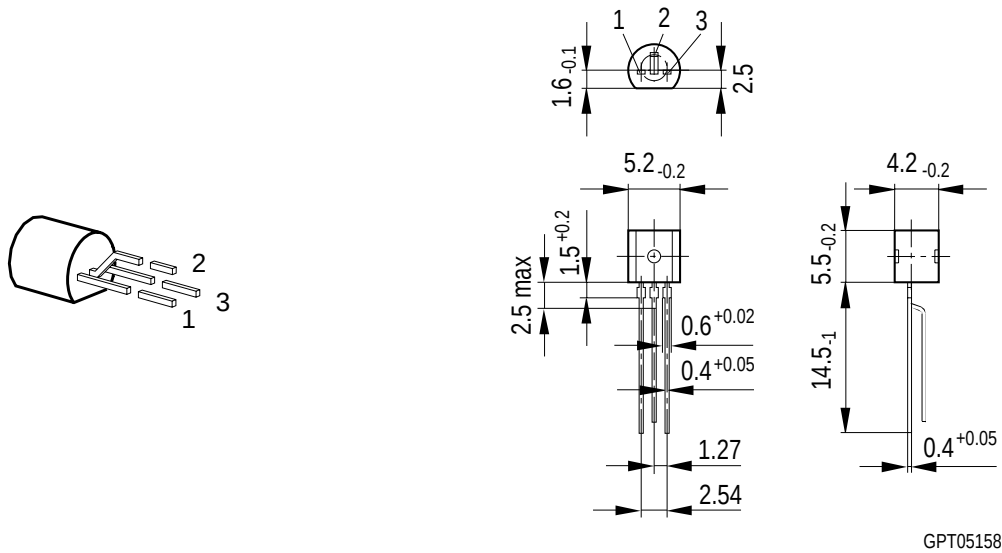


Bild 7

Figure 7

TO-92-E6288

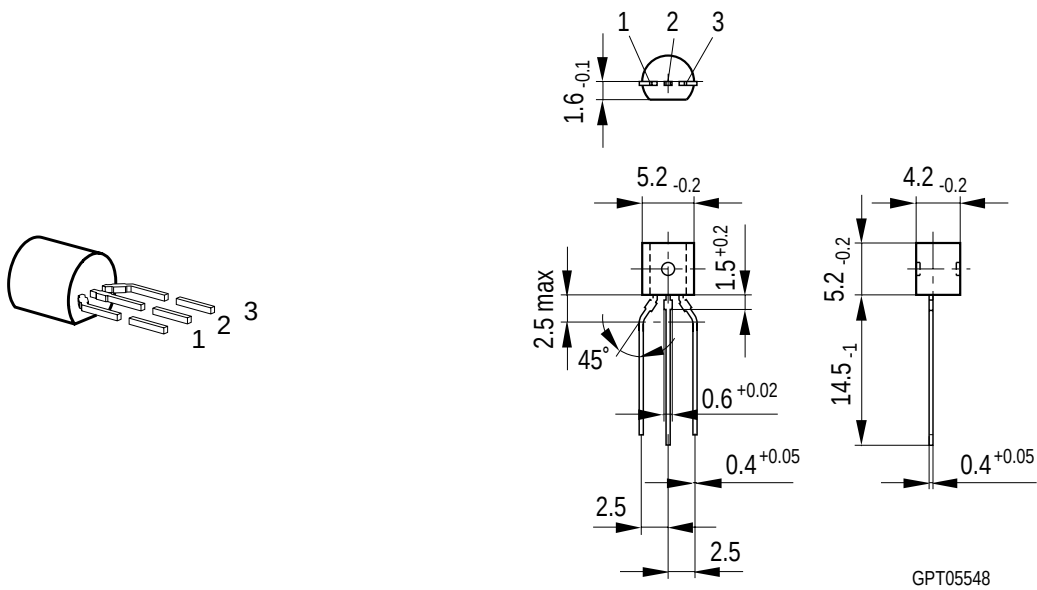
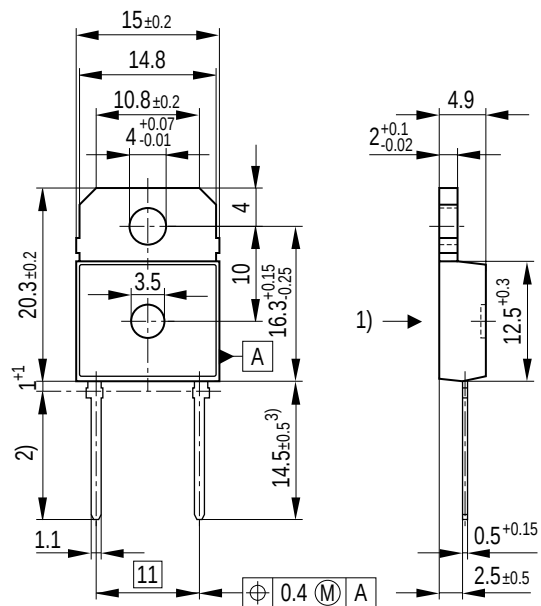
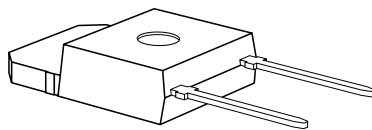


Bild 8

Figure 8

TO-218-2-1



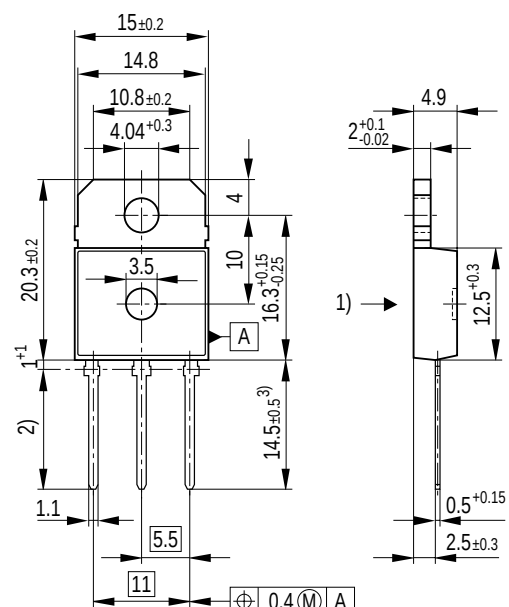
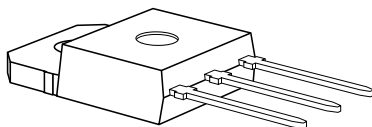
- 1) Punch direction, burr max. 0.04
- 2) Dip tinning
- 3) Max. 15.5 by dip tinning
press burr max. 0.05
radii not dimensioned max. 0.2

GPT05157

Bild 9

Figure 9

TO-218-3-1



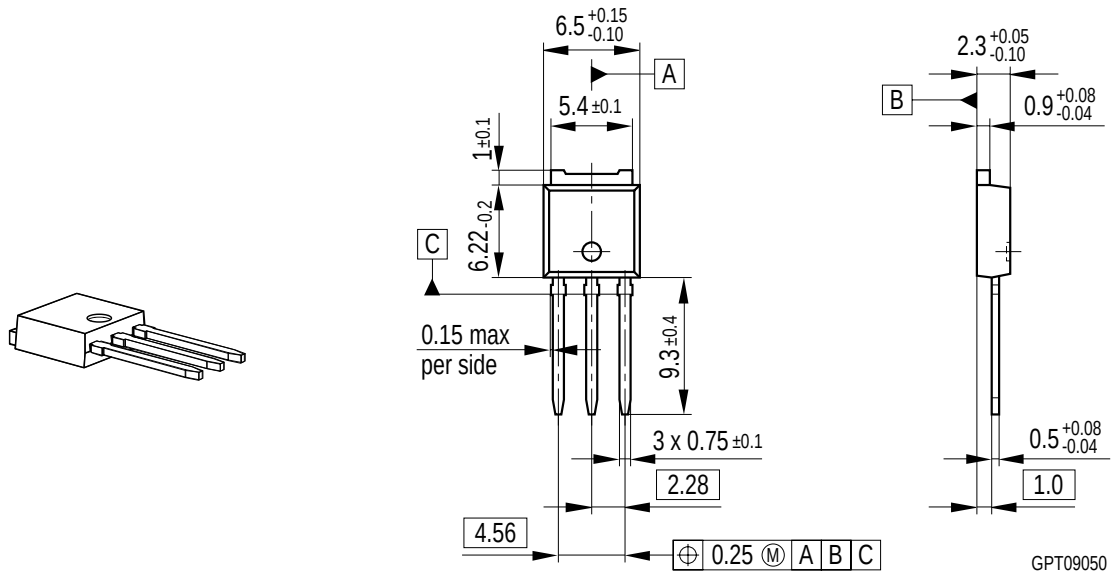
- 1) Punch direction, burr max. 0.04
- 2) Dip tinning
- 3) Max. 15.5 by dip tinning
press burr max. 0.05
radii not dimensioned max. 0.2

GPT05156

Bild 10

Figure 10

TO-251-3-1

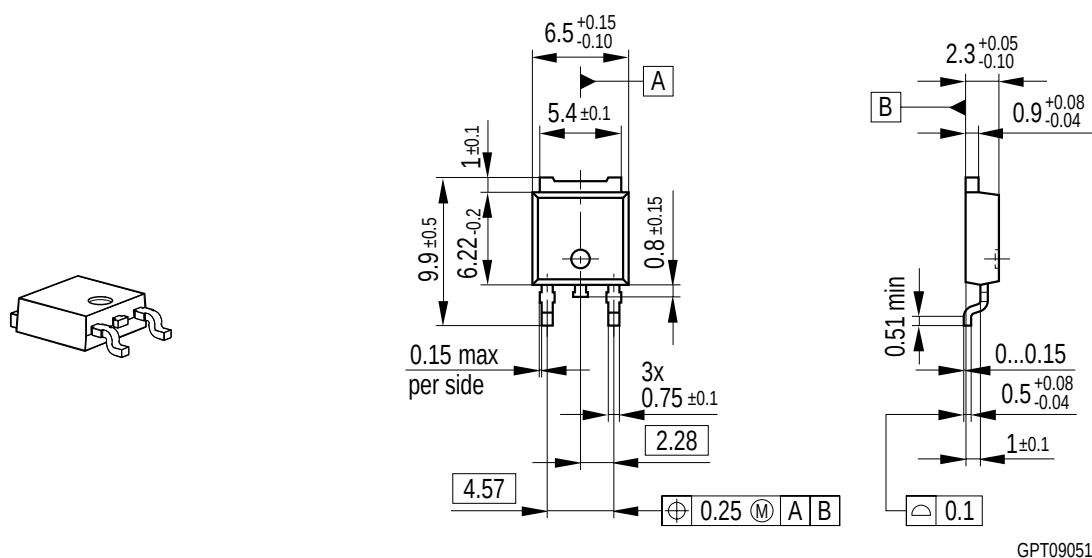


All metal surfaces tin plated, except area of cut.

Bild 11

Figure 11

TO-252-3-1

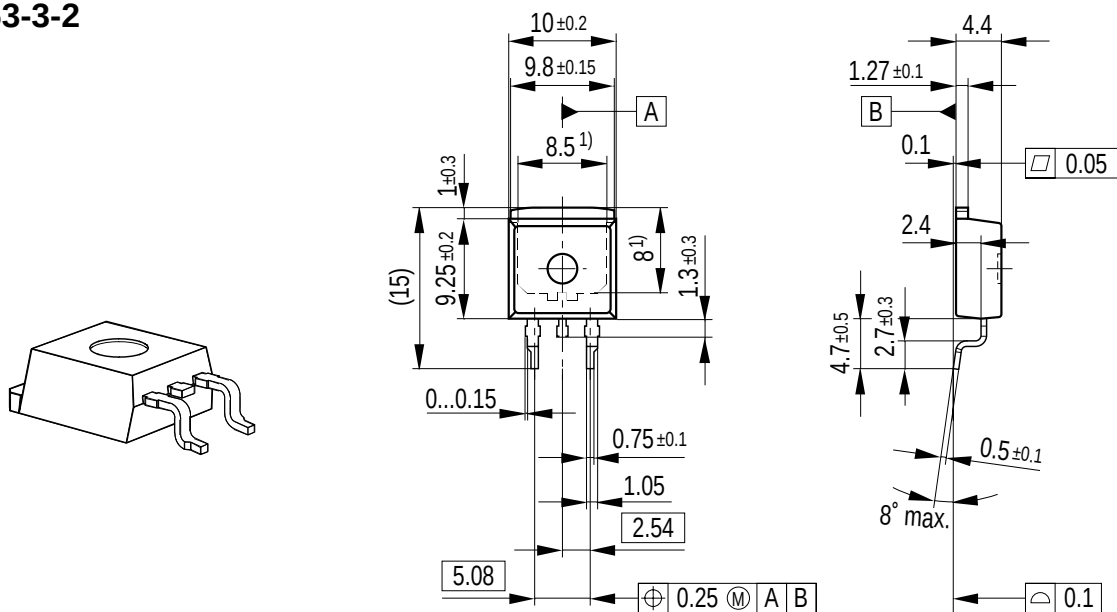


All metal surfaces tin plated, except area of cut.

Bild 12

Figure 12

TO-263-3-2



¹⁾ Typical

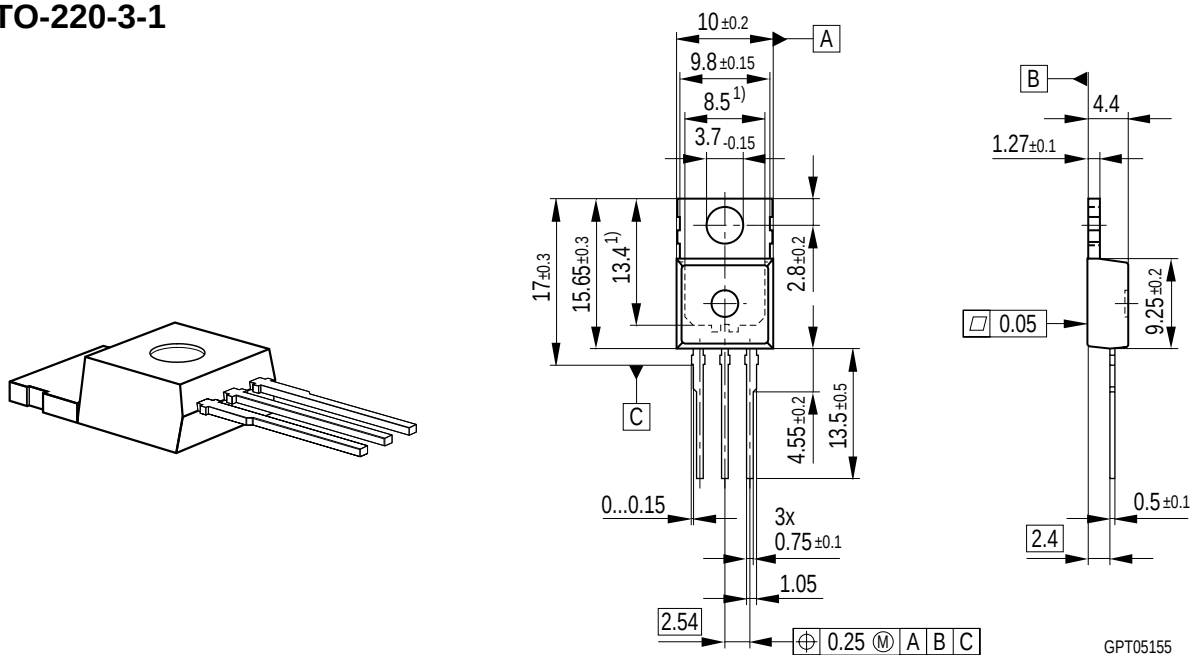
All metal surfaces tin plated, except area of cut.

GPT09085

Bild 13

Figure 13

TO-220-3-1



¹⁾ Typical

All metal surfaces tin plated, except area of cut.

GPT05155

Bild 14

Figure 14